

REMARKS

The allowability of claims 6-10 upon correction of the typographical error in claim 7 is acknowledged appreciatively and accepted above by combining claims and correcting the typographical error, which should not invoke any Festo-like considerations.

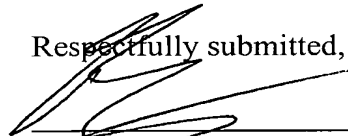
Nevertheless, the rejections of claims 5 and 11 under 35 USC 102 for anticipation by the cited Kamei, et al. patent publication are traversed. The patent publication discloses a first chip 3, a second chip 4 and a plate 61 (Fig. 2), but not a package structure.

Moreover, the first chip 3 of the patent publication and its second chip 4 are not adhered to the plate directly by adhesive as now recited in claims 5 and 11. Therefore, the rejection for anticipation is overcome.

The rejection for anticipation should not be converted into one under 35 USC 103 for obviousness from the patent publication, because of the difference in package structure teaching. As a result the patent publication does not teach toward or suggest the technical features of the claimed invention. Besides, the citation cannot achieve the objective of the claimed invention.

Reconsideration and allowance are, therefore, requested.

Respectfully submitted,



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